

1200V / 450A 半桥模块

PRODUCT FEATURES

- IGBT CHIP Trench+FS technology
- Vcesat with positive temperature coefficient
- Fast & soft recovery anti-parallel FWD
- High short circuit capability(10us)
- Low switching losses

APPLICATIONS


- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply


产品特性


- IGBT芯片采用Trench+FS技术
- Vcesat 具有正温度系数特性
- 快速且软恢复反并联二极管
- 高短路能力（10us）
- 低开关损耗


典型应用

- 电机驱动用变频器
- 交直流伺服驱动
- 不间断电源

技术信息 / Technical Information IGBT-模块 IGBT Module			 科微半导体 GrandSemi			
GF450B120T4						
IGBT芯片 最大额定值 / Maximum Rated Values						
项目/Item	条件/Conditions	符号/Symbol	值/Values			单位/Units
集电极-发射极电压 Collector-Emitter Breakdown Voltage	$T_J=25^{\circ}\text{C}$	V_{CES}	1200			V
连续集电极直流电流 DC Collector Current	$T_C=90^{\circ}\text{C}, T_{j,max}=175^{\circ}\text{C}$	I_C	450			A
	$T_C=25^{\circ}\text{C}, T_{j,max}=175^{\circ}\text{C}$		630			A
集电极重复峰值电流 Repetitive Peak Collector Current	$tp=1\text{ms}$	I_{CRM}	900			A
总功耗 Total Power Dissipation	$T_C=25^{\circ}\text{C}, T_{j,max}=175^{\circ}\text{C}$	P_{tot}	2142			W
栅极-发射极峰值电压 Gate-emitter peak voltage		V_{GES}	+/-20			V
特征值 / Characteristic Values						
项目/Item	条件/Conditions	符号/Symbol	值/Values			单位/Units
			Min	Typ	Max	
集电极-发射极饱和电压 Collector Emitter Saturation Voltage	$V_{GE}=15\text{V}, I_C=450\text{A}, T_J=25^{\circ}\text{C}$	$V_{CE(sat)}$		1.85	2.25	V
	$V_{GE}=15\text{V}, I_C=450\text{A}, T_J=125^{\circ}\text{C}$			2.15		
	$V_{GE}=15\text{V}, I_C=450\text{A}, T_J=150^{\circ}\text{C}$			2.2		
栅极阈值电压 Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=18\text{mA}$	$V_{GE(th)}$	5.0	5.8	6.5	V
栅极电荷 Gate Charge	$V_{CE}=600\text{V}, I_C=450\text{A}, V_{GE}=15\text{V}$	Q_G		2.25		μC
内部栅极电阻 Internal Gate Resistor		R_{Gint}		1.4		Ω
输入电容 Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$	C_{ies}		31.5		nF
反向传输电容 Reverse Transfer Capacitance		C_{res}		1.5		nF
集电极漏电流 Collector Leakage Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=25^{\circ}\text{C}$	I_{CES}			1	mA
栅极-发射极漏电流 Gate-Emitter Leakage Current	$V_{CE}=0\text{V}, V_{GE}=20\text{V}, T_J=25^{\circ}\text{C}$	I_{GES}			400	nA

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IGBT芯片 特征值 / Characteristic Values									
开通延迟时间 Turn on Delay Time	$V_{CC}=600V$ $I_C=450A$ $V_{GE}=\pm 15V$ $R_g=2.0\Omega$ Inductive Load	$T_J=125^\circ C$	$t_{d(on)}$		120		ns		
		$T_J=150^\circ C$			130				
上升时间 Rise Time			$T_J=125^\circ C$	t_r		86		ns	
			$T_J=150^\circ C$			86			
关断延迟时间 Turn off Delay Time			$T_J=125^\circ C$	$t_{d(off)}$		590		ns	
			$T_J=150^\circ C$			610			
下降时间 Fall Time			$T_J=125^\circ C$	t_f		200		ns	
			$T_J=150^\circ C$			220			
开通损耗能量 Turn on Energy	$V_{CC}=600V$ $I_C=450A$ $V_{GE}=\pm 15V$ $R_g=2.0\Omega$ Inductive Load	$T_J=125^\circ C$	E_{on}		39		mJ		
		$T_J=150^\circ C$			42				
关断损耗能量 Turn off Energy			$T_J=125^\circ C$	E_{off}		52		mJ	
			$T_J=150^\circ C$			56			
短路电流 Short Circuit Collector Current	$V_{GE}=15V, V_{CC}=800V,$ $t_{sc}\leq 10\mu s, T_J=150^\circ C$		I_{sc}		1700		A		
结-外壳热阻 Thermal resistance, junction to case			R_{thJC}			0.07	K/W		
在开关状态下温度 Temperature under switching conditions			T_{jop}	-40		150	$^\circ C$		

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Diode芯片 最大额定值 / Maximum Rated Values						
项目/Item	条件/Conditions	符号/Symbol	值/Values			单位/Units
反向重复峰值电压 Repetitive Peak Reverse Voltage	$T_J=25^{\circ}\text{C}$	V_{RRM}	1200			V
连续正向直流电流 Continuous DC Forward Current		I_F	400			A
正向重复峰值电流 Repetitive Peak Forward Current	$t_p=1\text{ms}$	I_{FRM}	800			A
I^2t 值 I^2t - value	$T_J=125^{\circ}\text{C}, t=10\text{ms}, V_R=0\text{V}$	I^2t	39200			A^2s
特征值 / Characteristic Values						
项目/Item	条件/Conditions	符号/Symbol	值/Values			单位/Units
			Min.	Typ.	Max.	
正向电压 Forward Voltage	$I_F=400\text{A}, V_{GE}=0\text{V}$	V_F		1.75	2.3	V
				1.5		
				1.45		
反向恢复电流 Reverse Recovery Current	$I_F=450\text{A}, V_R=600\text{V}, di_F/dt=-5300\text{A}/\mu\text{s}, T_J=150^{\circ}\text{C}$	I_{RRM}		485		A
反向恢复电荷 Reverse Recovery Charge		Q_{RR}		133		μC
反向恢复损耗 Reverse Recovery Energy		E_{rec}		59.5		mJ
结-外壳热阻 Thermal resistance, junction to case		R_{thJCD}			0.12	K/W
在开关状态下温度 Temperature under switching conditions		T_{jop}	-40		150	$^{\circ}\text{C}$

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GF450B120T4				
模块特性 / Module Characteristics				
项目/Item	条件/Conditions	符号/Symbol	值/Values	单位/Units
绝缘测试电压 Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	3000	V
储存温度 Storage Temperature		T _{stg}	-40 ~ 125	°C
相对电痕指数 Comparative tracking index		CTI	>225	
安装扭距 Mounting torque	To heatsink (M6 screw)	M	3 ~ 5	Nm
	To terminal (M6 screw)	M	2.5 ~ 5	Nm
重量 Weight		G	300	g



性能曲线 / Performance Curves

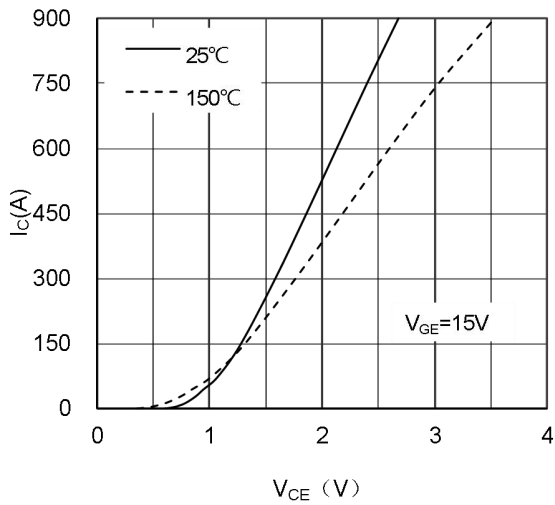


Figure 1. Typical Output Characteristics IGBT-inverter

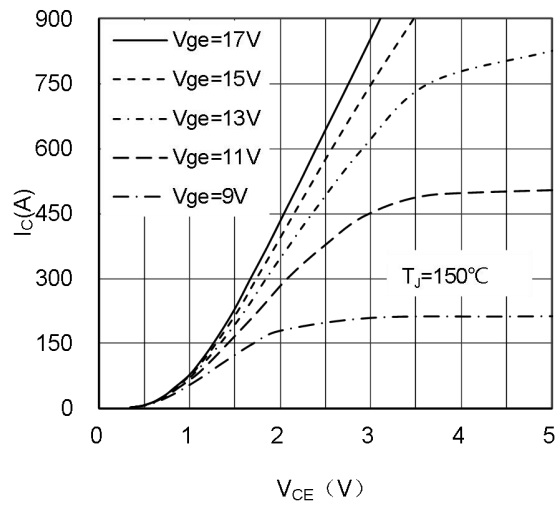


Figure 2. Typical Output Characteristics IGBT-inverter

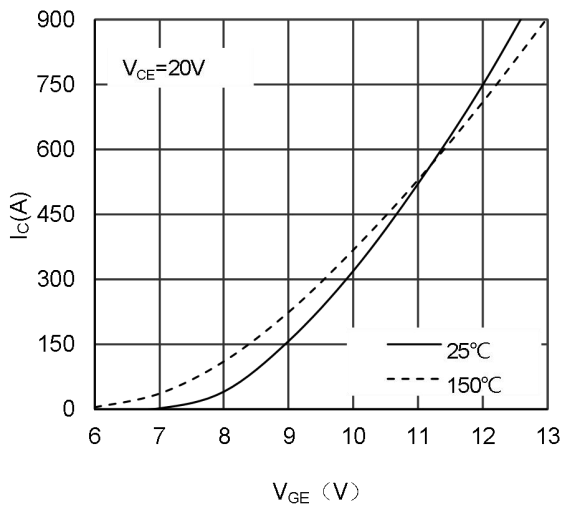


Figure 3. Typical Transfer characteristics IGBT-inverter

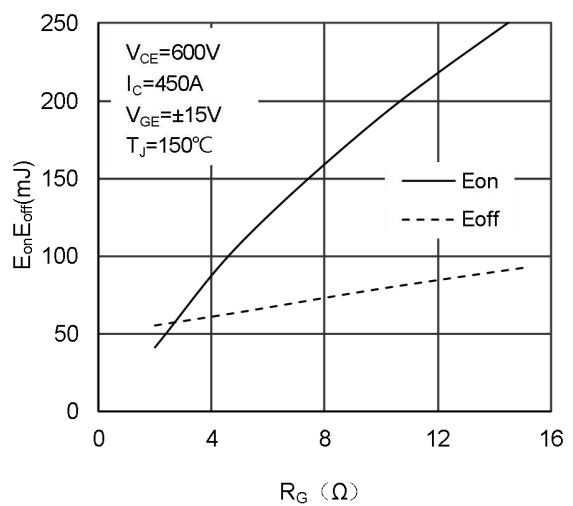


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

性能曲线 / Performance Curves

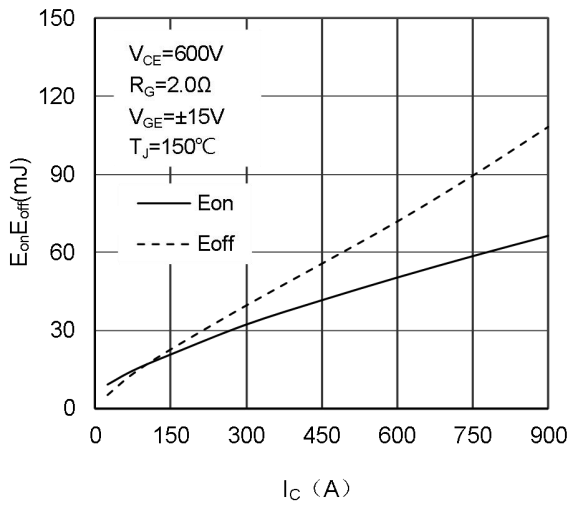


Figure 5. Switching Energy vs Collector Current IGBT-inverter

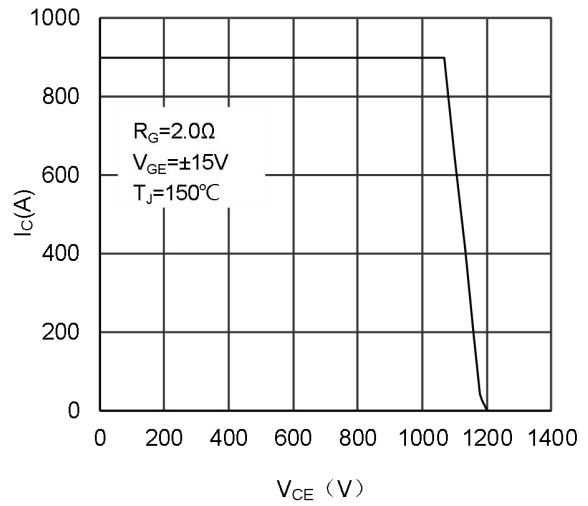


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

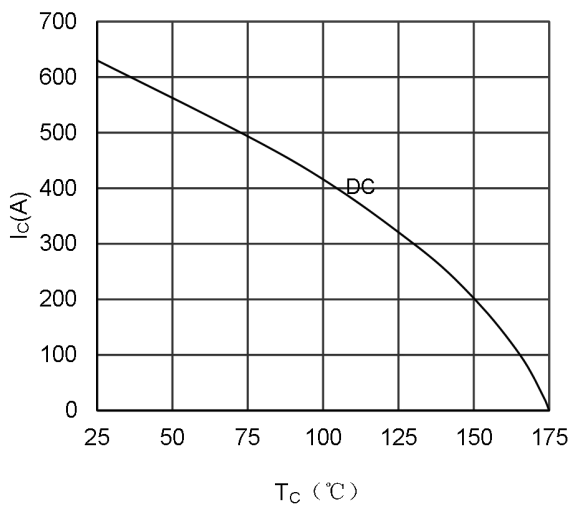


Figure 7. Collector Current vs Case temperature IGBT-inverter

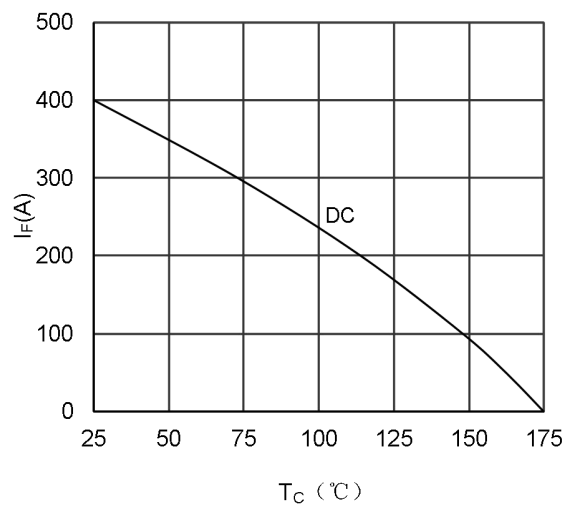


Figure 8. Forward current vs Case temperature Diode-inverter

性能曲线 / Performance Curves

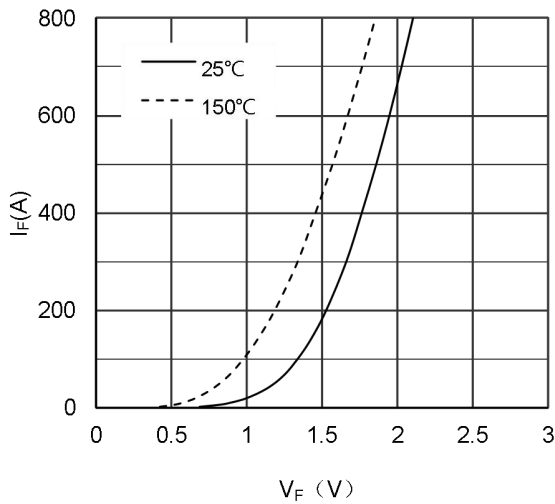


Figure 9. Diode Forward Characteristics Diode -inverter

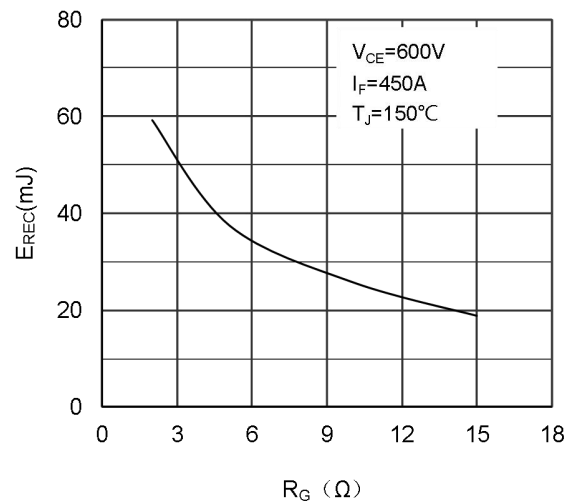


Figure 10. Switching Energy vs Gate Resistor Diode -inverter

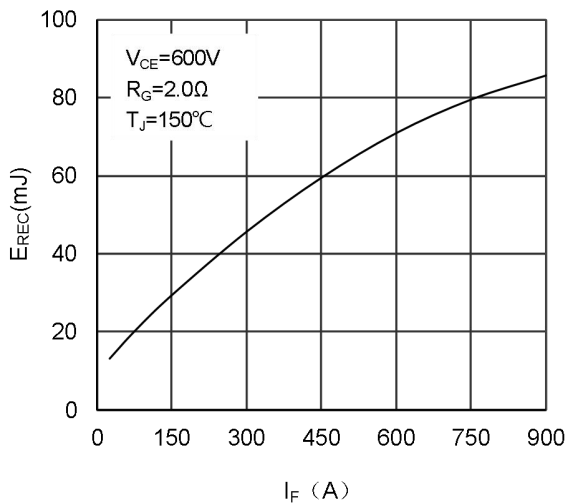


Figure 11. Switching Energy vs Forward Current Diode-inverter

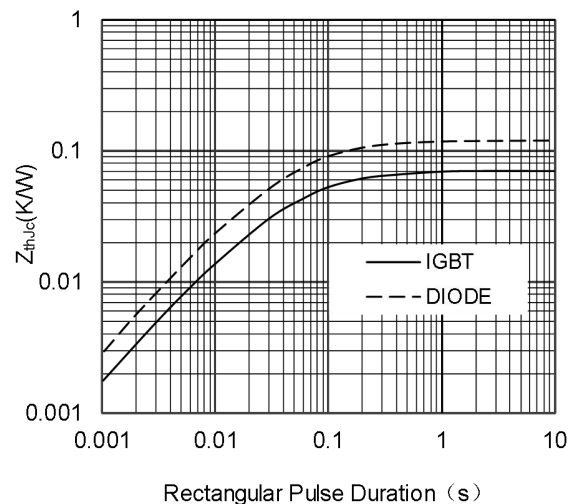


Figure 12. Transient Thermal Impedance of Diode and IGBT-inverter

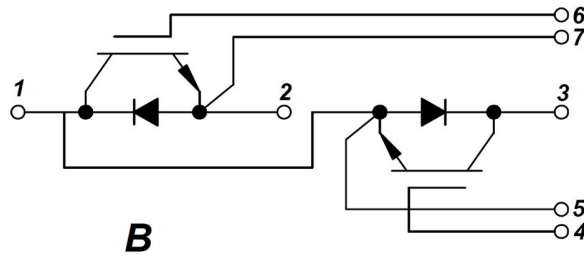
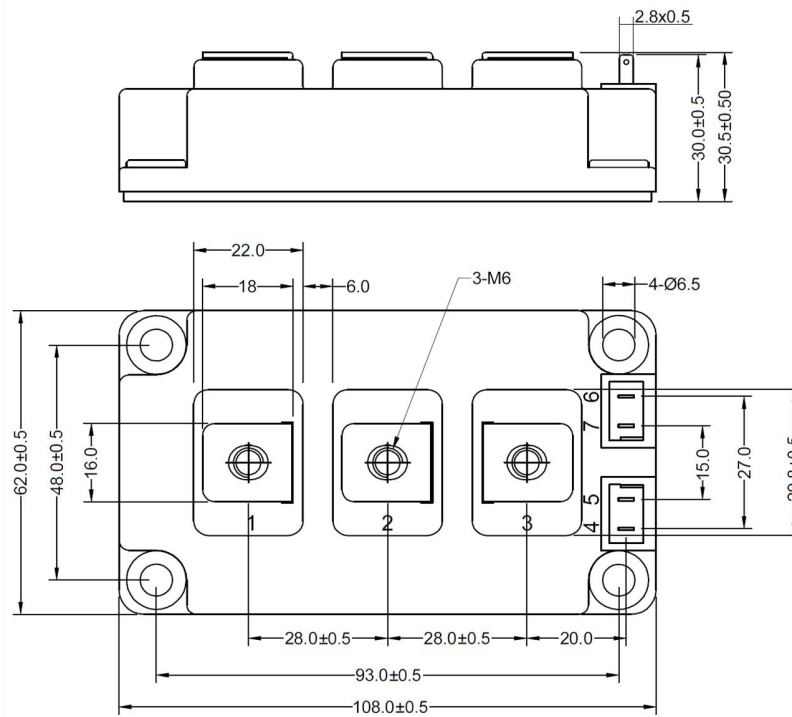


Figure 13. Circuit Diagram



Dimensions in (mm)
Figure 14. Package Outline